Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

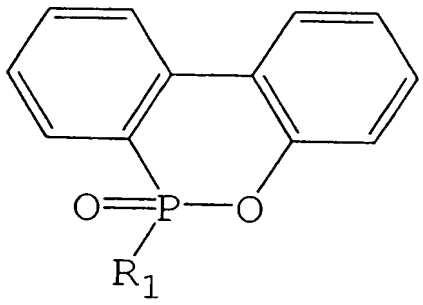
Listing of Claims:

1. (currently amended) A resin composition comprising:

an epoxy resin,

an amine-type curing agent,

an organophosphorous compound having a structure represented by formula 1:



Formula 1

wherein R_1 is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

wherein the epoxy resin and the ~~organophosphrous~~ organophosphorous compound have been compounded at a temperature of 50°C or lower, so as to inhibit reaction of said epoxy resin and said organophosphorous compound in the resin composition during the compounding.

2. (original) The resin composition according to claim 1, wherein the epoxy resin contains at least one epoxy resin selected from a phenol-novolak epoxy resin, a cresol-novolak epoxy resin and a dicyclopentadiene-modified novolak epoxy resin in an amount of 30 wt% or more versus the combined amount of the whole epoxy resin.

3. (original) The resin composition according to claim 1 or 2, wherein the amount of the amine-type curing agent compounded is from 0.3 to 0.6 equivalent per epoxy group of the epoxy resin.

4. (currently amended) The resin composition according to ~~any one of claims~~ claim 1 ~~to 3~~, wherein the amine-type curing agent is dicyanamide.

5. (currently amended) The resin composition according to ~~any one of claims~~ claim 1 ~~to 4~~, wherein the amount of the organophosphorous compound compounded is from 5 to 30 wt% versus the total amount of organic solids excluding the organic solvent.

6. (currently amended) The resin composition according to ~~any one of claims~~ claim 1 ~~to 5~~, wherein the organophosphorous compound is 10-(2,5-dihydroxyphenyl) - 9, 10-dihydro- 9-oxa-10-phosphaphenanthrene-10-oxide.

7. (currently amended) The resin composition according to ~~any one of claims~~ claim 1 ~~to 5~~, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

8. (previously presented) The resin composition according to claim 7, wherein the inorganic filler is aluminum hydroxide.

9. (currently amended) The resin composition according to claim 7 or 8, wherein a part of the inorganic filler is treated with zinc molybdate.

10. (currently amended) A prepreg obtainable by impregnating a substrate with the resin composition according to ~~any one of claims~~ claim 1 ~~to 9~~ or 7 and then drying the substrate impregnated with the resin composition.

11. (previously amended) A laminate comprising at least one prepreg according to claim 10 and at least one metal foil.

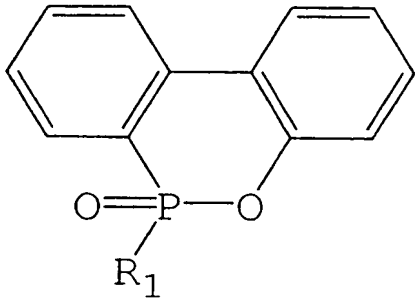
12. (currently amended) A printed wiring plate wherein the resin composition according to ~~any one of claims~~ claim 1 ~~to 9~~ or 7 is used as an insulating material substrate.

13. (currently amended) A method for producing a resin composition comprising:

an epoxy resin,

an amine-type curing agent,

an organophosphorous compound having a structure represented by formula 1:



Formula 1

wherein R_1 is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

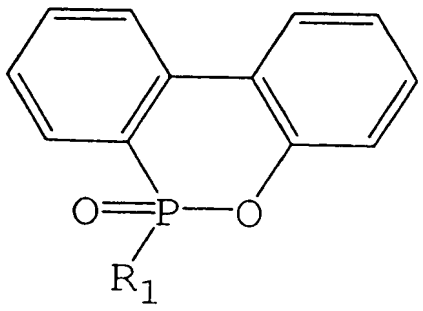
wherein the epoxy resin and the organophosphorous compound are compounded at a temperature of 50°C or lower, so as to inhibit reaction of said epoxy resin and said organophosphorous compound in the resin composition during the compounding.

14. (currently amended) A method for producing a resin composition comprising:

an epoxy resin,

an amine-type curing agent,

an organophosphorous compound having a structure represented by formula 1:



Formula 1

wherein R_1 is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

the method comprising:

allowing the epoxy resin and the amine-type curing agent to react in the organic solvent at a temperature of from 80 to 140°C,

whereby bringing the two components into a state where the two components are mutually compatible in the absence of a solvent, and then

compounding the organophosphorous compound to the reaction product at a temperature of 50°C or lower, so as to inhibit reaction of said epoxy resin and said organophosphorous compound in the resin composition during the compounding.

15. (currently amended) The method for producing a resin composition according to claim 13 ~~or 14~~, wherein the resin composition further comprises an inorganic filler.

16. (currently amended) A method for producing a prepreg, the method comprising:

using a resin composition prepared by the method according to ~~any one of claims~~ claim 13 ~~to 15~~ or 14 as resin varnish,

impregnating a substrate with this resin varnish, and then

drying the substrate impregnated with the resin varnish.

17. (currently amended) A method for producing a laminate, the method comprising arranging at least one metal foil on at least one prepreg prepared by the method according to claim 16, and heating and pressuring them to laminate together.

18. (original) A method for producing a printed-wiring board, the method comprising removing, by etching, an unnecessary part of the laminate prepared by the method according to claim 17.

19. (new) The resin composition according to claim 1, wherein in the resin composition, prior to use thereof in forming a prepreg, any reaction between the epoxy resin and the organophosphorous compound has been substantially completely avoided.

20. (new) The resin composition according to claim 1, wherein in the resin composition, prior to use thereof in forming a prepreg, a ratio of amount of the

organophosphorous compound that has reacted with the epoxy resin to amount of unreacted organophosphorous compound is at most 0.5%.

21. (new) The resin composition according to claim 2, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

22. (new) The resin composition according to claim 3, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

23. (new) The resin composition according to claim 4, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

24. (new) The resin composition according to claim 5, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

25. (new) The resin composition according to claim 6, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

26. (new) The resin composition according to claim 24, wherein the inorganic filler is aluminum hydroxide.

27. (new) The method for producing a resin composition according to claim 14, wherein the resin composition further comprises an inorganic filler.

28. (new) The resin composition according to claim 2, wherein the amine-type curing agent is dicyanamide.

29. (new) The resin composition according to claim 28, wherein the organophosphorous compound is 10-(2,5-dihydroxyphenyl) -9, 10-dihydro- 9-oxa-10-phosphaphenanthrene-10-oxide.

30. (new) The resin composition according to claim 29, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.

31. (new) The resin composition according to claim 30, wherein the inorganic filler is aluminum hydroxide.

32. (new) The resin composition according to claim 31, wherein a part of the inorganic filler is treated with zinc molybdate.

33. (new) The resin composition according to claim 32, wherein the amount of the amine-type curing agent compounded is from 0.3 to 0.6 equivalent per epoxy group of the epoxy resin.

34. (new) The resin composition according to claim 33, wherein the amount of the organophosphorous compound compounded is from 5 to 30 wt% versus the total amount of organic solids excluding the organic solvent.

35. (new) A prepreg obtainable by impregnating a substrate with the resin composition according to claim 32 and then drying the substrate impregnated with the resin composition.

36. (new) A laminate comprising at least one prepreg according to claim 35 and at least one metal foil.

37. (new) A printed wiring plate wherein the resin composition according to claim 32 is used as an insulating material substrate.

38. (new) The resin composition according to claim 28, further comprising at least one inorganic filler in an amount of from 10 to 50 wt% versus the total amount of the solid components excluding the organic solvent.